

PATENTPre
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 09/388,031

Filed: September 1, 1999

**For: METALLIZATION STRUCTURES
FOR SEMICONDUCTOR DEVICE
INTERCONNECTS, METHODS FOR
MAKING SAME, AND
SEMICONDUCTOR DEVICES
INCLUDING SAME**

Examiner: To be assigned

Group Art Unit: 2812

Attorney Docket No.: 3442US (96-428)

CERTIFICATE OF MAILING

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Joseph A. Walkowski
Typed/printed name of person whose signature is contained above

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PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to the examination of the claims on the merits in the above-referenced application, please amend this application as follows:

IN THE SPECIFICATION:

On page 2, line 18, insert --and-- after "features";

On page 4, line 3, delete the comma after "resistivity" and insert commas after "and" and "therefore";